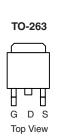
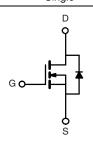


Vishay Siliconix

# Automotive N-Channel 100 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	100		
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0105		
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.012		
I <sub>D</sub> (A)	100		
Configuration	Single		





N-Channel MOSFET

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- · Package with Low Thermal Resistance
- AEC-Q101 Qualifiedd
- 100 % R<sub>q</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



**FREE** 

ORDERING INFORMATION	
Package	TO-263
Lead (Pb)-free and Halogen-free	SQM85N10-10-GE3

ABSOLUTE MAXIMUM RATING	$\bullet$ (1C = 25 °C, unles	s otnerwise noted	D)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	100	V	
Gate-Source Voltage		$V_{GS}$	V <sub>GS</sub> ± 20		
Continuous Drain Current	$T_C = 25  ^{\circ}C^a$	1	100		
	T <sub>C</sub> = 125 °C	- I <sub>D</sub>	70		
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	100	А	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	400		
Single Pulse Avalanche Current	. 0.4	I <sub>AS</sub>	75		
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	280	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	D	375	w	
	T <sub>C</sub> = 125 °C	$P_{D}$	125		
Operating Junction and Storage Temperatur	e Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient F	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	40	°C/W	
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.4		

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- c. When mounted on 1" square PCB (FR-4 material).
- d. Parametric verification ongoing.



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PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static	•						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = 250 \mu A$		100	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$		1.5	2.0	2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Zero Gate Voltage Drain Current		$V_{GS} = 0 V$	V <sub>DS</sub> = 100 V	-	-	1.0	μА
	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 125 °C	-	-	50	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 175 °C	-	-	500	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	120	-	-	Α
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A	-	0.007	0.0105	Ω
	В	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C	-	-	0.02	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C	-	-	0.026	
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 20 A	-	0.008	0.012	
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A		-	115	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>		V <sub>DS</sub> = 25 V, f = 1 MHz	-	6440	8050	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	655	820	
Reverse Transfer Capacitance	C <sub>rss</sub>	1		-	315	395	
Total Gate Charge <sup>c</sup>	Qg			-	122	185	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 50 \text{ V}, I_{D} = 85 \text{ A}$	-	23	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	28	-	
Gate Resistance	R <sub>g</sub>	f = 1 MHz		0.8	1.7	2.6	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	13	20	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, \text{ R}_L = 0.6 \Omega$ $I_D \cong 85 \text{ A}, \text{ V}_{GEN} = 10 \text{ V}, \text{ R}_g = 2.5 \Omega$		-	14	21	- ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	44	66	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	10	15	
Source-Drain Diode Ratings and Char-	acteristics <sup>b</sup>	•			•	•	
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	400	Α
Forward Voltage	V <sub>SD</sub>	$I_F = 85 \text{ A}, V_{GS} = 0$		-	0.9	1.5	V

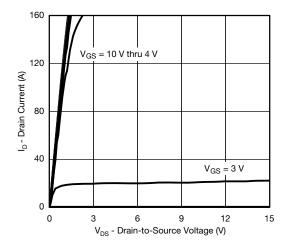
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,~duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

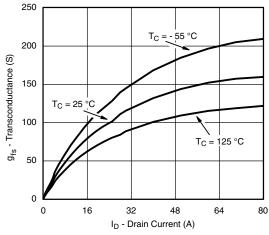
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



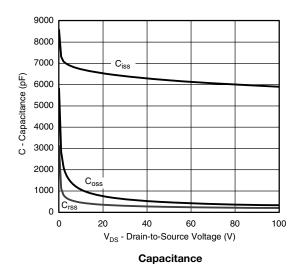
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

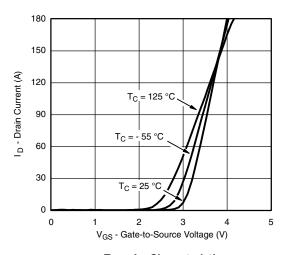


#### **Output Characteristics**

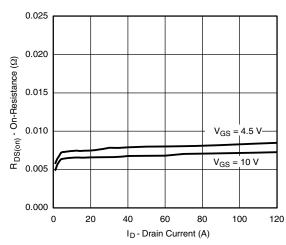


### Transconductance

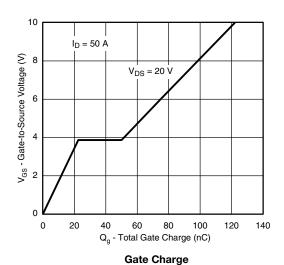




#### **Transfer Characteristics**

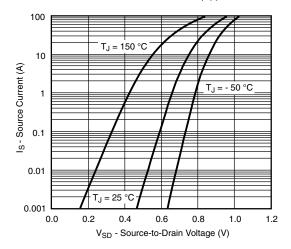


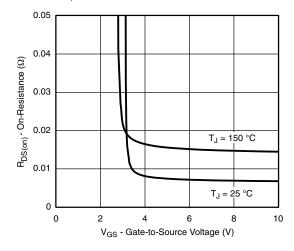
**On-Resistance vs. Drain Current** 



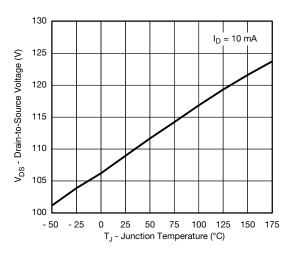


### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

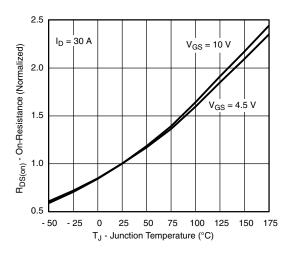




**Source Drain Diode Forward Voltage** 

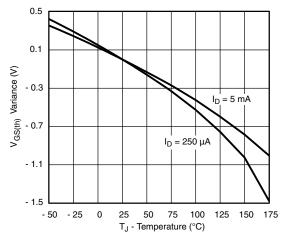


On-Resistance vs. Gate-to-Source Voltage



**Breakdown Voltage vs. Junction Temperature** 

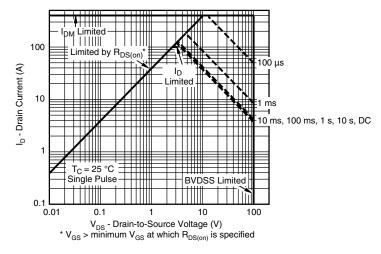
Normalized On-Resistance vs. Junction Temperature



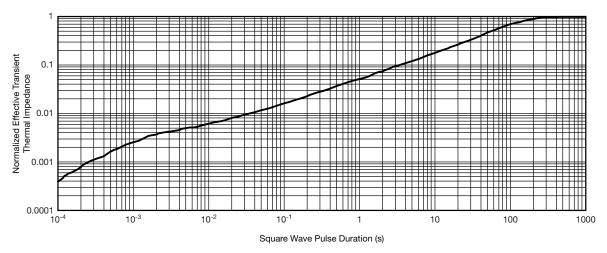
Threshold Voltage Variance vs. Junction Temperature



### **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



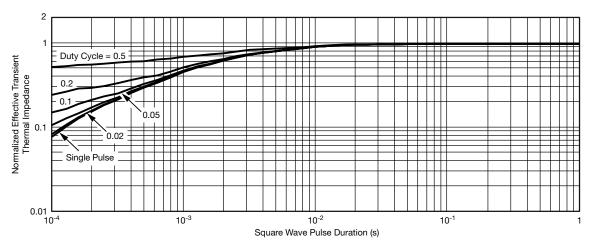
#### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



### THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

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